

### Pin Out







# Pin Description

Pin Name	Pin #	Туре	Description				
RA1+, RA1-	78, 77	LVDS IN					
RB1+, RB1-	80, 79	LVDS IN					
RC1+, RC1-	83, 82	LVDS IN	The 1st Link. The 1st pixel input data when Dual Link.				
RD1+, RD1-	87, 86	LVDS IN					
RCLK1+, RCLK1-	85, 84	LVDS IN	LVDS Clock Input for 1st Link.				
RA2+, RA2-	90, 89	LVDS IN					
RB2+, RB2-	92, 91	LVDS IN					
RC2+, RC2-	95, 94	LVDS IN	The 2nd Link. These pins are disabled when Single Link.				
RD2+, RD2-	99, 98	LVDS IN					
RCLK2+, RCLK2-	97, 96	LVDS IN	LVDS Clock Input for 2nd Link.				
R17 ~ R10	52, 51, 50, 47, 46, 45, 44, 43	OUT					
G17 ~ G10	62, 61, 60, 59, 58, 55, 54, 53	OUT	The 1st Pixel Data Outputs.				
B17 ~ B10	72, 71, 68, 67, 66, 65, 64, 63	OUT					
R27 ~ R20	19, 18, 17, 14, 13, 12, 11, 10	OUT					
G27 ~ G20	29, 26, 25, 24, 23, 22, 21, 20	OUT	The 2nd Pixel Data Outputs.				
B27 ~ B20	39, 38, 37, 36, 35, 32, 31, 30	OUT					
DE	75	OUT	Data Enable Output.				
VSYNC	74	OUT	Vsync Output.				
HSYNC	73	OUT	Hsync Output.				
CLKOUT	40	OUT	Clock Output.				
DRVSEL	9	IN	Output Driverbility Select.DRVSELclockdataH8mA4mAL4mA2mA				
R/F	8	IN	Output Clock Triggering Edge Select. H: Rising edge, L: Falling edge.				
MODE1, MODE0	6, 5	IN	Mode   MODE1 MODE0 Mode   L L Dual Link (Dual-in/Dual-out)   L H Single Link(Single-in/Dual-out)   other Not Available				
/PDWN	4	IN	H: Normal operation, L: Power down (all outputs are pulled to ground)				
VCC	15, 27, 33, 41, 48, 56, 69	Power	Power Supply Pins for TTL outputs and digital circuitry.				
GND	3, 7, 16, 28, 34, 42, 49, 57, 70	Ground	Ground Pins for TTL outputs and digital circuitry.				
LVDS VCC	81,93	Power	Power Supply Pins for LVDS inputs.				
LVDS GND	76, 88, 100	Ground	Ground Pins for LVDS inputs.				





Pin Name	Pin #	Туре	Description
PLL VCC	2	Power	Power Supply Pin for PLL circuitry.
PLL GND	1	Ground	Ground Pin for PLL circuitry.

# Absolute Maximum Ratings<sup>1</sup>

Supply Voltage (V <sub>CC</sub> )	-0.3V ~ +4.0V
CMOS/TTL Input Voltage	$-0.3V \sim (V_{CC} + 0.3V)  ( \le 4.0V)$
CMOS/TTL Output Voltage	$-0.3V \sim (V_{CC} + 0.3V)  ( \le 4.0V)$
LVDS Receiver Input Voltage	$-0.3V \sim (V_{CC} + 0.3V)  (\le 4.0V)$
Output Current	-15mA ~ 15mA
Junction Temperature	+125°C
Storage Temperature Range	-55°C ~+125°C
Maximum Power Dissipation @+25 °C	1.7W

## **Electrical Characteristics**

## CMOS/TTL DC Specifications

		Vo	$_{\rm CC} = 3.0 \mathrm{V}$	~ 3.6V, 7	$\Gamma a = -10 ^{\circ}C$	~ +70°C
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V <sub>IH</sub>	High Level Input Voltage		2.0		V <sub>CC</sub>	V
V <sub>IL</sub>	Low Level Input Voltage		GND		0.8	V
SymbolParaVIHHigh Level InpVILLow Level InpVOHHigh Level OuVOLLow Level Out	High Lovel Output Veltage	I <sub>OH</sub> = -2mA, -4mA (data)	2.4			V
	High Level Output vohage	$I_{OH}$ = -4mA, -8mA (clock)	2.4			v
V <sub>OL</sub>	Low Lovel Output Voltage	$I_{OL}$ = 2mA, 4mA (data)			0.4	V
	Low Lever Output voltage	$I_{OL}$ = 4mA, 8mA (clock)			0.4	

## LVDS Receiver DC Specifications

Input Current

I<sub>INC</sub>

#### $V_{CC} = 3.0V \sim 3.6V, Ta = -10^{\circ}C \sim +70^{\circ}C$

 $\pm 10$ 

μΑ

	-			-		
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V <sub>TH</sub>	Differential Input High Threshold	V <sub>IC</sub> = 1.2V			100	mV
V <sub>TL</sub>	Differential Input Low Threshold	V <sub>IC</sub> = 1.2V	-100			mV
I	Input Cumont	$V_{IN} = 2.4 V / 0 V$			1.20	μΑ
I <sub>INL</sub>	input Current	V <sub>CC</sub> = 3.6V			±20	

 $0V \le V_{IN} \le V_{CC}$ 

<sup>1. &</sup>quot;Absolute Maximum Ratings" are those valued beyond which the safety of the device can not be guaranteed. They are not meant to imply that the device should be operated at these limits. The tables of "Electrical Characteristics" specify conditions for device operation.



# Supply Current

 $V_{CC}=3.0V \thicksim 3.6V, \ Ta=-10^{\circ}C \ \thicksim+70^{\circ}C$ 

Symbol	Parameter	Condition(*)			Max.	Units
-	Receiver Supply		MODE<1:0>=LL			
I <sub>RCCW</sub>	Current	$f_{CLKOUT} = 85MHz$	CL=8pF,		225	mA
	(Worst Case Pattern)		Vcc=3.6V			
I <sub>RCCS</sub>	Receiver Power Down Supply Current	/PDWN = L			10	μΑ

# Switching Characteristics

	$V_{CC} = 3.0V \sim 3.6V, Ta = -10 \circ C \sim$					
Symbol	Par	ameter	Min.	Тур.	Max.	Units
t	CL KOUT Deried	Dual-in / Dual-out	11.76	t <sub>RCIP</sub>	40.0	ns
<sup>4</sup> RCP	CLKOUT Fellod	Single-in / Dual-out	17.85	2t <sub>RCIP</sub>	5V, $Ta = -10 \circ C$ Max. 40.0 80.0 40.0 40.0 40.0 40.0 40.0 40.0 40.0 40.0 40.25 +t <sub>SK</sub> $\frac{t_{RCIP}}{7} + t_{SK}$ $2\frac{t_{RCIP}}{7} + t_{SK}$ $3\frac{t_{RCIP}}{7} + t_{SK}$ $3\frac{t_{RCIP}}{7} + t_{SK}$ $\frac{1}{7} + t_$	ns
t <sub>RCH</sub>	CLKOUT High Tin	me		$\frac{t_{RCP}}{2}$		ns
t <sub>RCL</sub>	CKLOUT Low Tir	ne		$\frac{t_{RCP}}{2}$		ns
t <sub>RS</sub>	TTL Data Setup to	CLKOUT	0.3t <sub>RCP</sub> -0.5			ns
t <sub>RH</sub>	TTL Data Hold fro	m CKLOUT	0.3t <sub>RCP</sub> -0.5			ns
t <sub>TLH</sub>	TTL Low to High	Transition Time		2.5	4.0	ns
t <sub>THL</sub>	TTL High to Low	Transition Time		2.5	4.0	ns
ter	Receiver Skew	CLKIN=85MHz	-0.40		+0.40	ns
-3K	Margin	CLKIN=112MHz	-0.25		+0.25	ns
t <sub>RIP1</sub>	Input Data Position	10	-t <sub>SK</sub>	0.0	$+t_{SK}$	ns
t <sub>RIP0</sub>	Input Data Positior	11	$\frac{t_{RCIP}}{7} - t_{SK}$	$\frac{t_{RCIP}}{7}$	$\frac{t_{RCIP}}{7} + t_{SK}$	ns
t <sub>RIP6</sub>	Input Data Position2		$2\frac{t_{RCIP}}{7} - t_{SK}$	$2\frac{t_{RCIP}}{7}$	$2\frac{t_{RCIP}}{7} + t_{SK}$	ns
t <sub>RIP5</sub>	Input Data Positior	13	$3\frac{t_{RCIP}}{7} - t_{SK}$	$3\frac{t_{RCIP}}{7}$	$3\frac{t_{RCIP}}{7} + t_{SK}$	ns
t <sub>RIP4</sub>	Input Data Positior	n4	$4\frac{t_{RCIP}}{7} - t_{SK}$	$4\frac{t_{RCIP}}{7}$	$4\frac{t_{RCIP}}{7} + t_{SK}$	ns
t <sub>RIP3</sub>	Input Data Positior	15	$5\frac{t_{RCIP}}{7} - t_{SK}$	$5\frac{t_{RCIP}}{7}$	$5\frac{t_{RCIP}}{7} + t_{SK}$	ns
t <sub>RIP2</sub>	Input Data Position6		$6\frac{t_{RCIP}}{7} - t_{SK}$	$6\frac{t_{RCIP}}{7}$	$6\frac{t_{RCIP}}{7} + t_{SK}$	ns
t <sub>RPLL</sub>	Phase Lock Loop S	Set			10.0	ms
t <sub>RCIP</sub>	CLKIN Period		8.92		40.0	ns
t <sub>CK12</sub>	Skew Time betwee RCLK2	n RCLK1 and			±0.3t <sub>RCIP</sub>	ns





## AC Timing Diagrams

TTL Outputs





Phase Lock Loop Set Time







## Pixel Map Table for Single/Dual Link

1st Pixel Data				2nd Pixel Data			
924 A TTI OutputDin	TF	TFT Panel Data		924 A TTI Output Din	TFT Panel Data		
824A TILOutputPin		24Bit	18Bit	824A TTLOutputPili		24Bit	18Bit
R10	LSB	R10	-	R20	LSB	R20	-
R11		R11	-	R21		R21	-
R12		R12	R10	R22		R22	R20
R13		R13	R11	R23		R23	R21
R14		R14	R12	R24		R24	R22
R15		R15	R13	R25		R25	R23
R16		R16	R14	R26		R26	R24
R17	MSB	R17	R15	R27	MSB	R27	R25
G10	LSB	G10	-	G20	LSB	G20	-
G11		G11	-	G21		G21	-
G12		G12	G10	G22		G22	G20
G13		G13	G11	G23		G23	G21
G14		G14	G12	G24		G24	G22
G15		G15	G13	G25		G25	G23
G16		G16	G14	G26		G26	G24
G17	MSB	G17	G15	G27	MSB	G27	G25
B10	LSB	B10	-	B20	LSB	B20	-
B11		B11	-	B21		B21	-
B12		B12	B10	B22		B22	B20
B13		B13	B11	B23		B23	B21
B14		B14	B12	B24		B24	B22
B15		B15	B13	B25		B25	B23
B16		B16	B14	B26		B26	B24
B17	MSB	B17	B15	B27	MSB	B27	B25





## 824A TTL Data Output Timing for Single/Dual Link Example : SXGA(1280 x 1024)



TFT Panel (1280 x 1024)



**THine**<sup>®</sup>

AC Timing Diagrams





Note:  $V_{diff} = (Ryx+) - (Ryx-), (RCLKx+) - (RCLKx-)$ 





### LVDS Data Inputs Timing Diagrams in Single Link







#### LVDS Data Inputs Timing Diagrams in Dual Link







#### Note

1)Power On Sequence

Power on LVDS-Tx after THC63LVD824A. If it is not avoidable, please contact to

mspsupport@thine.co.jp (for FAE mailing list)

#### 2)Cable Connection and Disconnection

Don't connect and disconnect the LVDS cable , when the power is supplied to the system.

#### 3)GND Connection

Connect the each GND of the PCB which LVDS-Tx and THC63LVD824A on it. It is better for EMI reduction to place GND cable as close to LVDS cable as possible.

#### 4)Multi Drop Connection

Multi drop connection is not recommended.



#### 5)Asynchronous use

Asynchronous use such as following systems are not recommended. If it is not avoidable, please contact to

mspsupport@thine.co.jp (for FAE mailing list)









# Package



UNITS:mm

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